

**Amendments to the Specification:**

Please replace the title on page 1 with the following amended title:

**--CIRCUIT DEVICE WITH CONDUCTIVE PATTERNS SEPARATED BY  
INSULATING RESIN-FILLED GROOVES--**

Please replace the paragraph beginning at page 1, line 22, with the following amended paragraph:

--Fig. 13 shows a CSP 66, which is slightly larger than a chip size and employs a glass epoxy substrate ~~[[5]]~~ 65 as the supporting substrate. Here, a description shall be provided for the case where a transistor chip T is mounted onto glass epoxy substrate 65.--

Please replace the paragraph beginning at page 2, line 23, with the following amended paragraph:

--However, the above-described CSP 66 uses a glass substrate 65 as an interposer and this places on limit on making CSP 66 more compact and thinner. A circuit device 80, with which such a mounting substrate is made unnecessary as shown in ~~Fig. 15~~ Fig. 14, has thus been developed.--